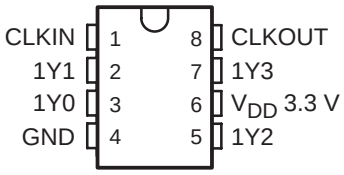
- **Phase-Lock Loop Clock Driver for Synchronous DRAM and General-Purpose Applications**
- **Spread Spectrum Clock Compatible**
- **Operating Frequency: 24 MHz to 200 MHz**
- **Low Jitter (Cycle-cycle): <|150 ps| Over the Range 66 MHz−200 MHz**
- **Distributes One Clock Input to One Bank of Five Outputs (CLKOUT Is Used to Tune the Input-Output Delay)**
- **Three-States Outputs When There Is no Input Clock**
- **Operates From Single 3.3-V Supply**
- **Available in 8-Pin TSSOP and 8-Pin SOIC Packages**
- **Consumes Less Than 100 μA (Typically) in Power Down Mode**
- **Internal Feedback Loop Is Used to Synchronize the Outputs to the Input Clock**
- **25-Ω On-Chip Series Damping Resistors**
- **Integrated RC PLL Loop Filter Eliminates the Need for External Components**

D OR PW PACKAGE
(TOP VIEW)



description

The CDCVF2505 is a high-performance, low-skew, low-jitter, phase-lock loop (PLL) clock driver. It uses a PLL to precisely align, in both frequency and phase, the output clocks (1Y[0−3] and CLKOUT) to the input clock signal (CLKIN). The CDCVF2505 operates at 3.3 V. It also provides integrated series-damping resistors that make it ideal for driving point-to-point loads.

One bank of five outputs provides low-skew, low-jitter copies of CLKIN. Output duty cycles are adjusted to 50 percent, independent of duty cycle at CLKIN. The device automatically goes in power-down mode when no input signal is applied to CLKIN.

Unlike many products containing PLLs, the CDCVF2505 does not require an external RC network. The loop filter for the PLLs is included on-chip, minimizing component count, space, and cost.

Because it is based on the PLL circuitry, the CDCVF2505 requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization is required following power up and application of a fixed-frequency, fixed-phase signal at CLKIN, and following any changes to the PLL reference.

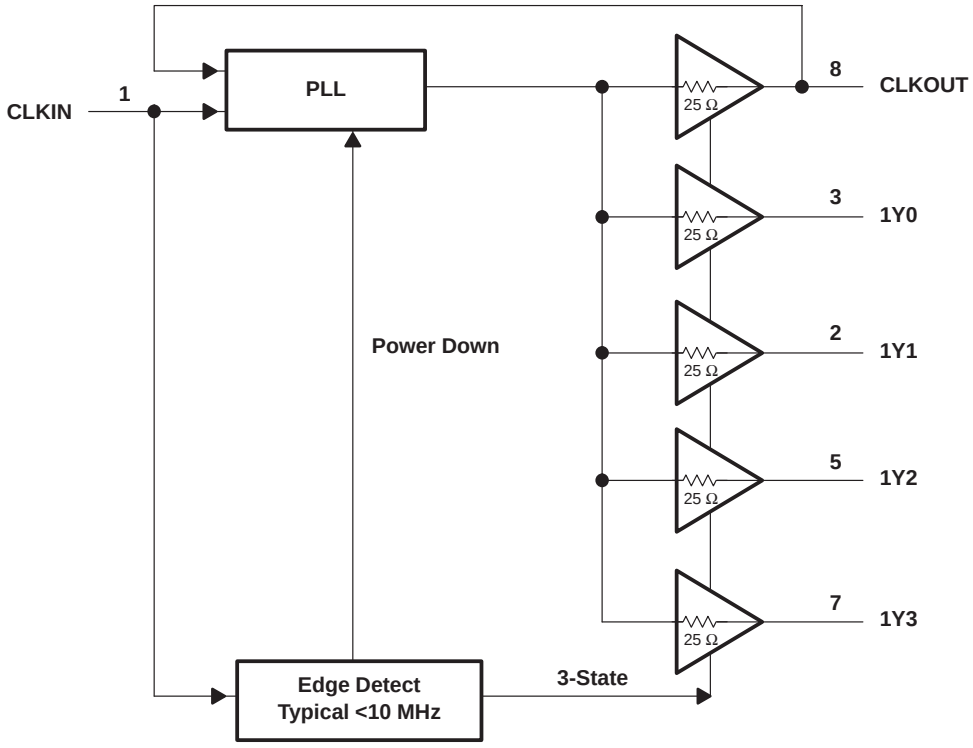
The CDCVF2505 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE

INPUT	OUTPUTS	
CLKIN	1Y (0:3)	CLKOUT
L	L	L
H	H	H
<10 MHz†	Z	Z

† Typically, below 2 MHz the device goes in power-down mode in which the PLL is turned off and the outputs enter into Hi-Z mode. If a >10-MHz signal is applied at CLKIN the PLL turns on, reacquires lock, and stabilizes after approximately 100 μs. The outputs will then be enabled.

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
1Y[0−3]	2, 3, 5, 7	O	Clock outputs. These outputs are low-skew copies of CLKIN. Each output has an integrated 25-Ω series damping resistor.
CLKIN	1	I	Clock input. CLKIN provides the clock signal to be distributed by the CDCVF2505 clock driver. CLKIN is used to provide the reference signal to the integrated PLL that generates the clock output signals. CLKIN must have a fixed frequency and fixed phase for the PLL to obtain phase lock. Once the circuit is powered up and a valid signal is applied, a stabilization time (100 μs) is required for the PLL to phase lock the feedback signal to CLKIN.
CLKOUT	8	O	Feedback output. CLKOUT completes the internal feedback loop of the PLL. This connection is made inside the chip and an external feedback loop should NOT be connected. CLKOUT can be loaded with a capacitor to achieve zero delay between CLKIN and the Y outputs.
GND	4	Power	Ground
$V_{DD3.3V}$	6	Power	3.3-V Supply

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V_{DD} . . . . . −0.5 V to 4.3 V
Input voltage range, V_I (see Notes 1 and 2) . . . . . −0.5 V to V_{DD} + 0.5 V
Output voltage range, V_O (see Notes 1 and 2) . . . . . −0.5 V to V_{DD} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) . . . . . ±50 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) . . . . . ±50 mA
Continuous total output current, I_O (V_O = 0 to V_{DD}) . . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package . . . . . 165.5°C/W
PWR package . . . . . 230.5°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 4.3 V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	3	3.3	3.6	V
High-level input voltage, V_{IH}	0.7 V_{DD}			V
Low-level input voltage, V_{IL}			0.3 V_{DD}	V
Input voltage, V_I	0		V_{DD}	V
High-level output current, I_{OH}			−12	mA
Low-level output current, I_{OL}			12	mA
Operating free-air temperature, T_A	−40		85	°C

timing requirements over recommended ranges of supply voltage and operating free-air temperature

			MIN	NOM	MAX	UNIT
f_{clk}	Clock frequency		24		200	MHz
	Input clock duty cycle	24 MHz − 85 MHz (see Note 4)	30%		85%	
		86 MHz − 200 MHz	40%	50%	60%	
	Stabilization time (see Note 5)				100	µs

NOTES: 4. Ensured by design but not 100% production tested.
5. Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLKIN. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V_{DD}	MIN	TYP†	MAX	UNIT
V_{IK}	Input voltage		I_I = −18 mA	3 V			−1.2	V
V_{OH}	High-level output voltage		I_{OH} = −100 µA	MIN to MAX	V_{DD}−0.2			V
			I_{OH} = −12 mA	3 V	2.1			
			I_{OH} = −6 mA	3 V	2.4			
V_{OL}	Low-level output voltage		I_{OL} = 100 µA	MIN to MAX			0.2	V
			I_{OL} = 12 mA	3 V			0.8	
			I_{OL} = 6 mA	3 V			0.55	
I_{OH}	High-level output current		V_O = 1 V	3 V	−27			mA
			V_O = 1.65 V	3.3 V		−36		
I_{OL}	Low-level output current		V_O = 2 V	3 V	27			mA
			V_O = 1.65 V	3.3 V		40		
I_I	Input current		V_I = 0 V or V_{DD}				±5	µA
C_i	Input capacitance		V_I = 0 V or V_{DD}	3.3 V		4.2		pF
C_o	Output capacitance	Yn	V_I = 0 V or V_{DD}	3.3 V		2.8		pF
		CLKOUT				5.2		

† All typical values are at respective nominal V_{DD} and 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 25 pF, V_{DD} = 3.3 V ± 0.3 V (see Note 5)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{pd}	Propagation delay (normalized (see Figure 3)	CLKIN to Yn, f= 66 MHz to 200 MHz	−150		150	ps
$t_{sk(o)}$	Output skew (see Note 6)	Yn to Yn			150	ps
$t_{c(jit\_cc)}$	Jitter (cycle to cycle) (see Figure 5)	f = 66 MHz to 200 MHz		70	150	ps
		f = 24 MHz to 50 MHz		200	400	
odc	Output duty cycle (see Figure 4)	f = 24 MHz to 200 MHz at 50% V_{DD}	45%		55%	
t_r	Rise time	V_O = 0.4 V to 2 V	0.5		2	ns
t_f	Fall time	V_O = 2 V to 0.4 V	0.5		2	ns

† All typical values are at respective nominal V_{DD} and 25°C.
NOTE 6: The $t_{sk(o)}$ specification is only valid for equal loading of all outputs.

ESD information

ESD MODELS	LIMIT
Human Body Model (HBM)	2.0 kV
Machine Model (MM)	300 V
Charge Device Model (CDM)	1 kV

thermal information

CDCVF2505 8-PIN SOIC			THERMAL AIR FLOW (CFM)				UNIT
			0	150	250	500	
$R_{\theta JA}$	High K		97	87	83	77	°C/W
$R_{\theta JA}$	Low K		165	126	113	97	°C/W
$R_{\theta JC}$	High K	39					°C/W
$R_{\theta JC}$	Low K	42					°C/W

CDCVF2505 8-PIN TSSOP			THERMAL AIR FLOW (CFM)				UNIT
			0	150	250	500	
$R_{\theta JA}$	High K		149	142	138	132	°C/W
$R_{\theta JA}$	Low K		230	185	170	150	°C/W
$R_{\theta JC}$	High K	65					°C/W
$R_{\theta JC}$	Low K	69					°C/W

TYPICAL CHARACTERISTICS

t_{pd}, PROPAGATION DELAY TIME
vs
DELTA LOAD (TYPICAL VALUES @ 3.3 V, 25°C)
CLOCK FREQUENCY, f = 100 MHz

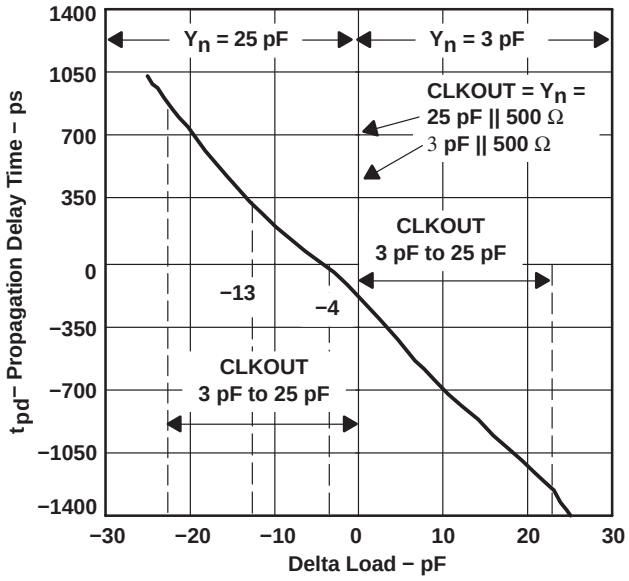


Figure 1

t_{pd}, PROPAGATION DELAY TIME
vs
FREQUENCY (TYPICAL VALUES @ 3.3 V, 25°C)

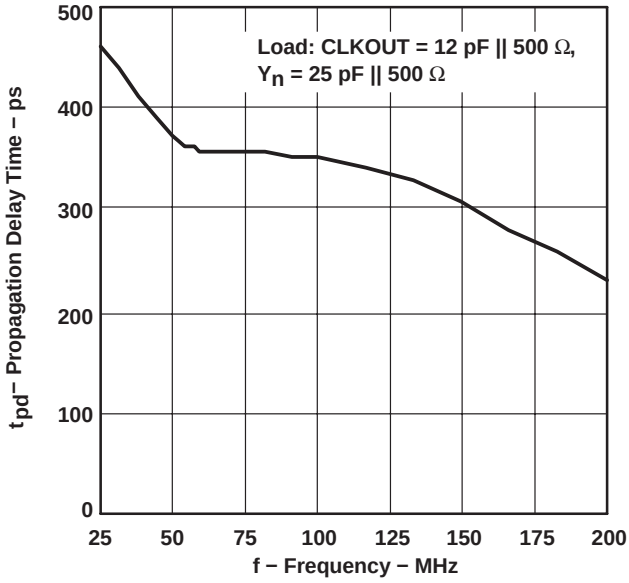


Figure 2

NOTE: Delta Load = CLKOUT Load − Yn Load

TYPICAL CHARACTERISTICS

t_{pd}, TYPICAL PROPAGATION DELAY TIME
vs
FREQUENCY(TUNED FOR MINIMUM DELAY)

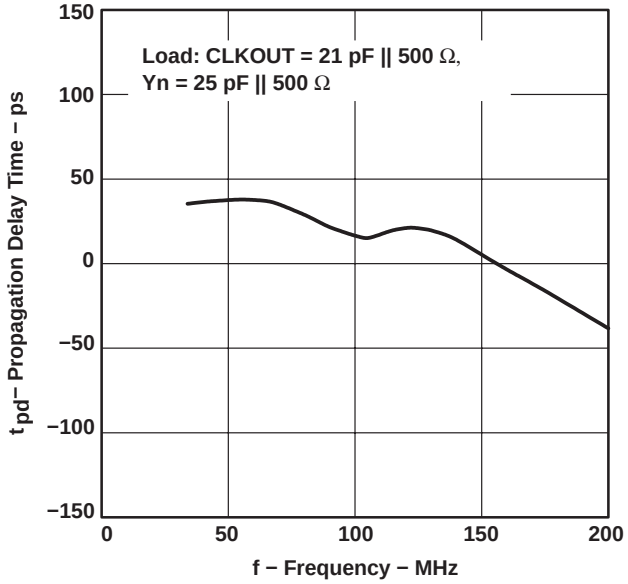


Figure 3

DUTY CYCLE
vs
FREQUENCY

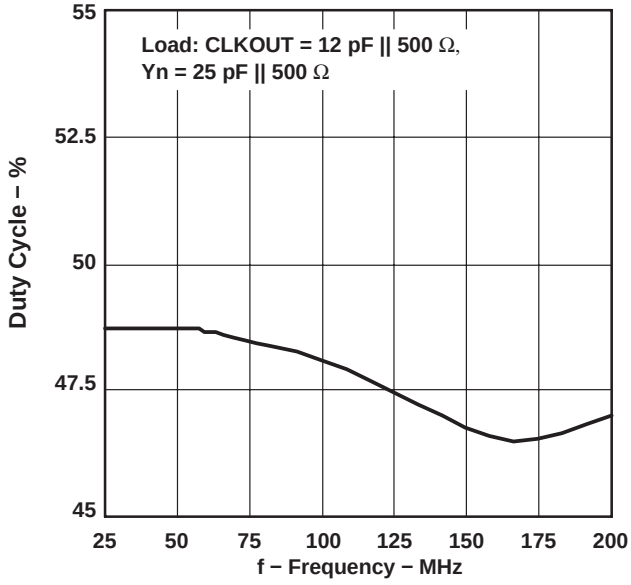


Figure 4

CYCLE−CYCLE JITTER
vs
FREQUENCY

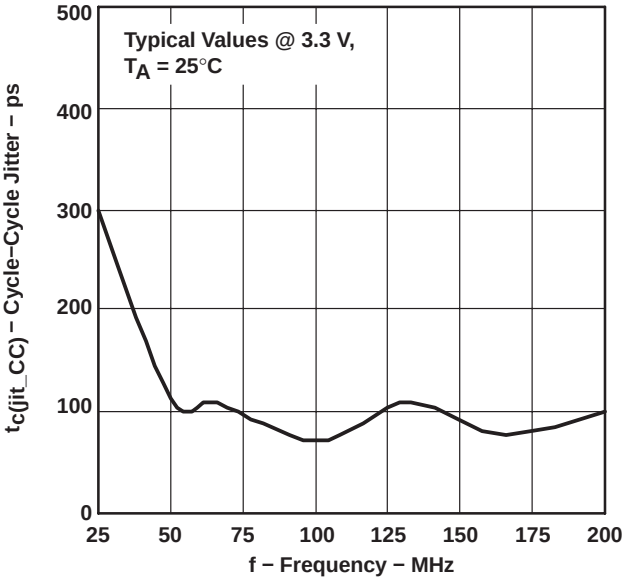


Figure 5

I_{CC}, SUPPLY CURRENT
vs
FREQUENCY

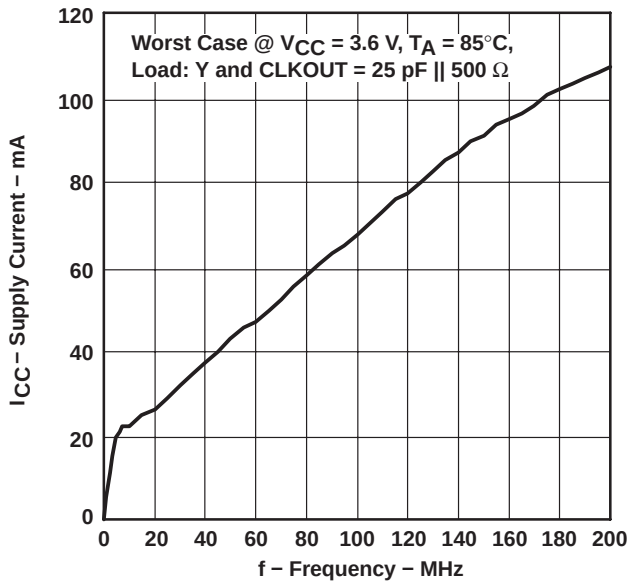


Figure 6

PARAMETER MEASUREMENT INFORMATION

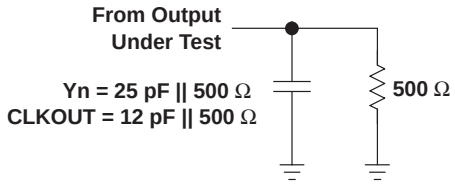


Figure 7. Test Load Circuit

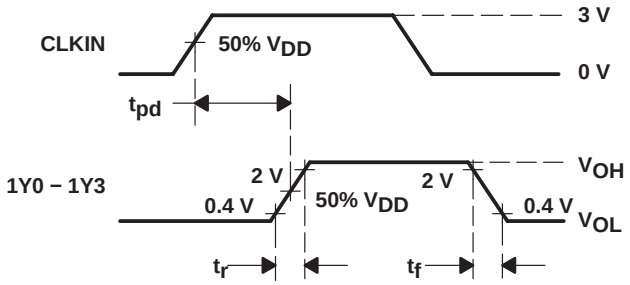


Figure 8. Voltage Threshold for Measurements, Propagation Delay (t_{pd})

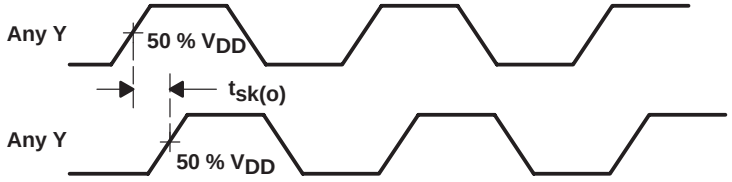


Figure 9. Output Skew

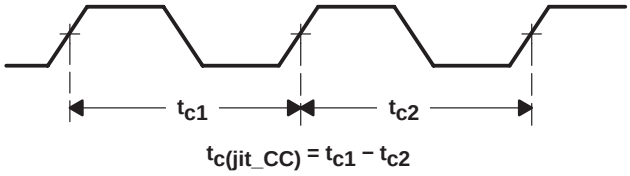


Figure 10. Cycle-to-Cycle Jitter

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CDCVF2505D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CKV05	Samples
CDCVF2505DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CKV05	Samples
CDCVF2505DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CKV05	Samples
CDCVF2505DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CKV05	Samples
CDCVF2505PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CKV05	Samples
CDCVF2505PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CKV05	Samples
CDCVF2505PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CKV05	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

OTHER QUALIFIED VERSIONS OF CDCVF2505 :

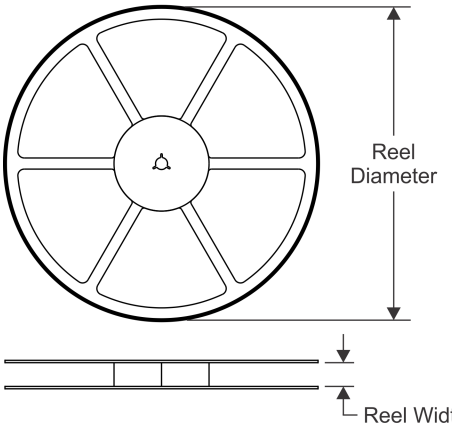
- Automotive: CDCVF2505-Q1

NOTE: Qualified Version Definitions:

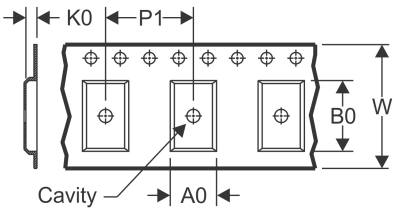
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

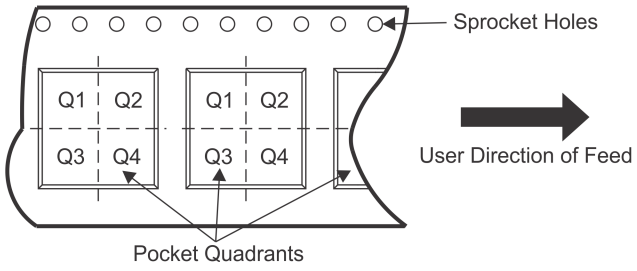


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

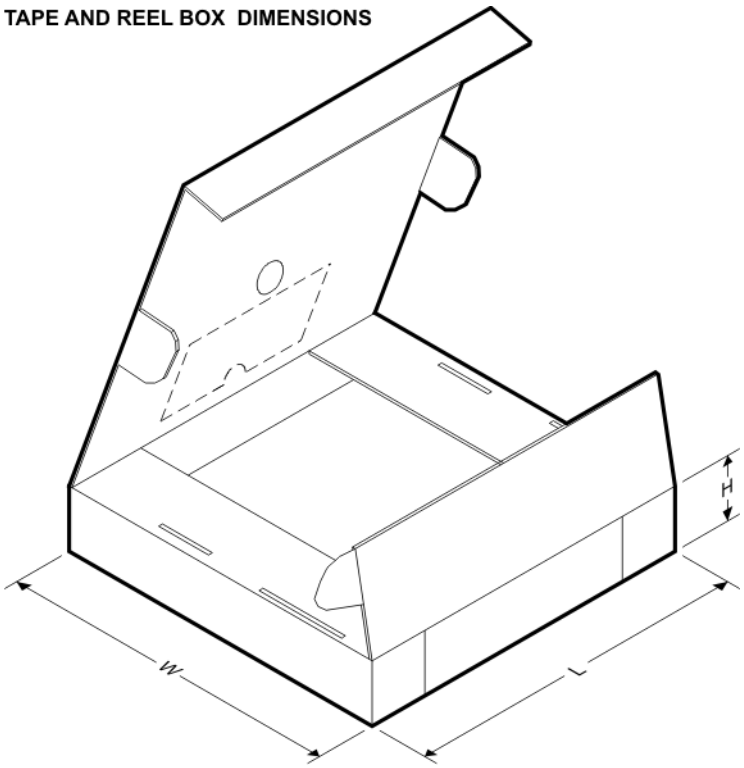
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCVF2505DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
CDCVF2505PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

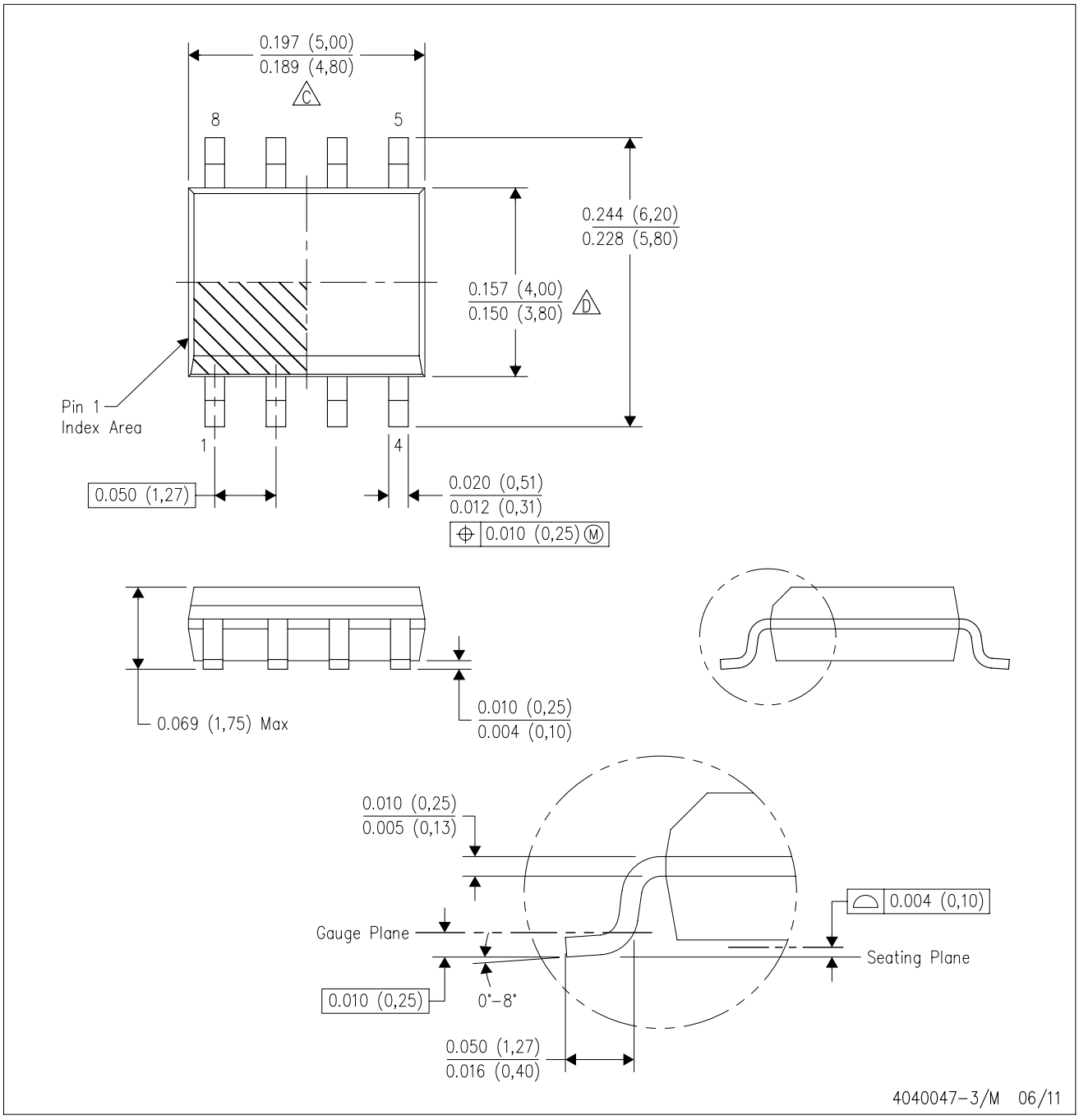
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

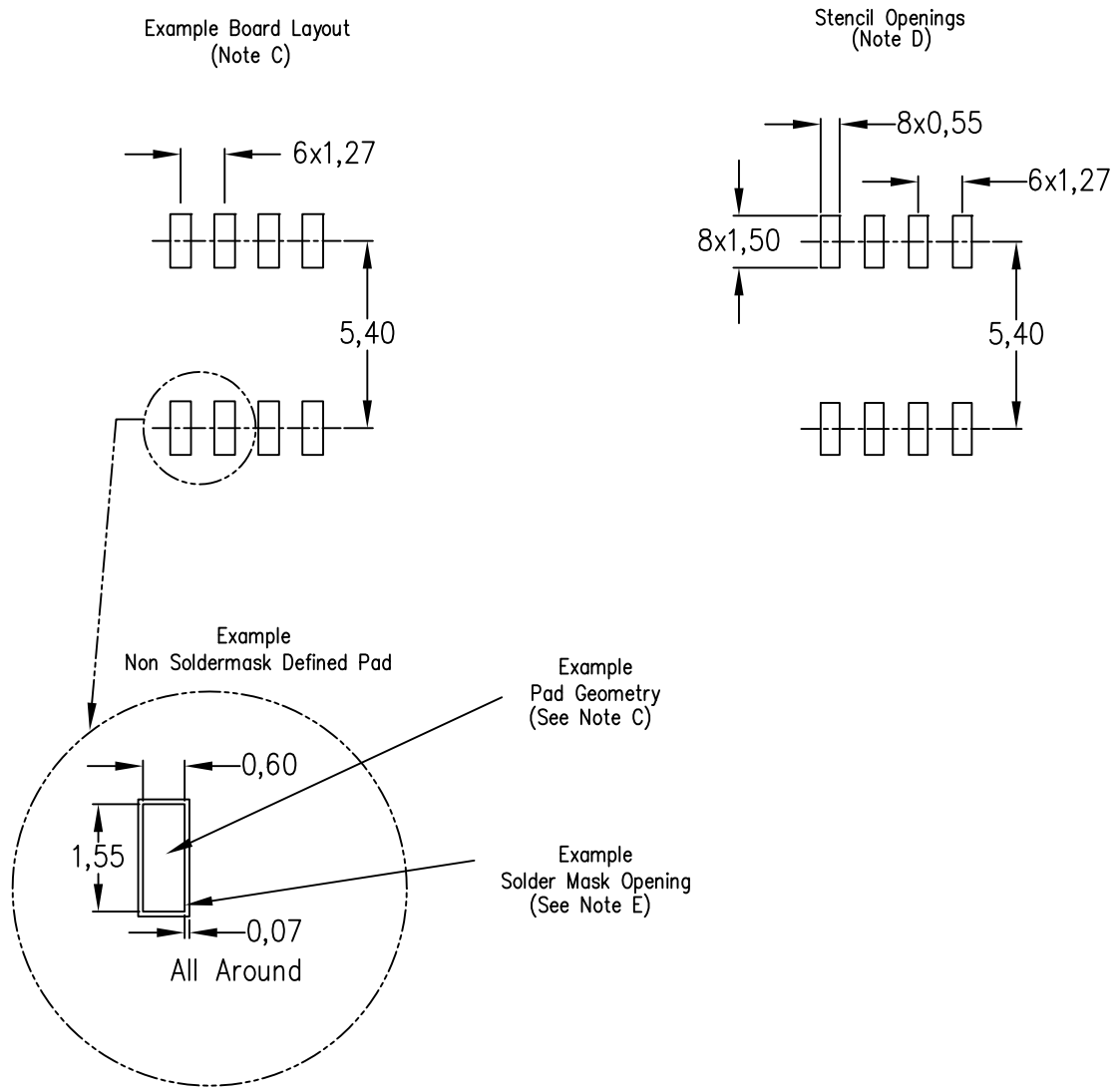
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCVF2505DR	SOIC	D	8	2500	367.0	367.0	35.0
CDCVF2505PWR	TSSOP	PW	8	2000	367.0	367.0	35.0

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



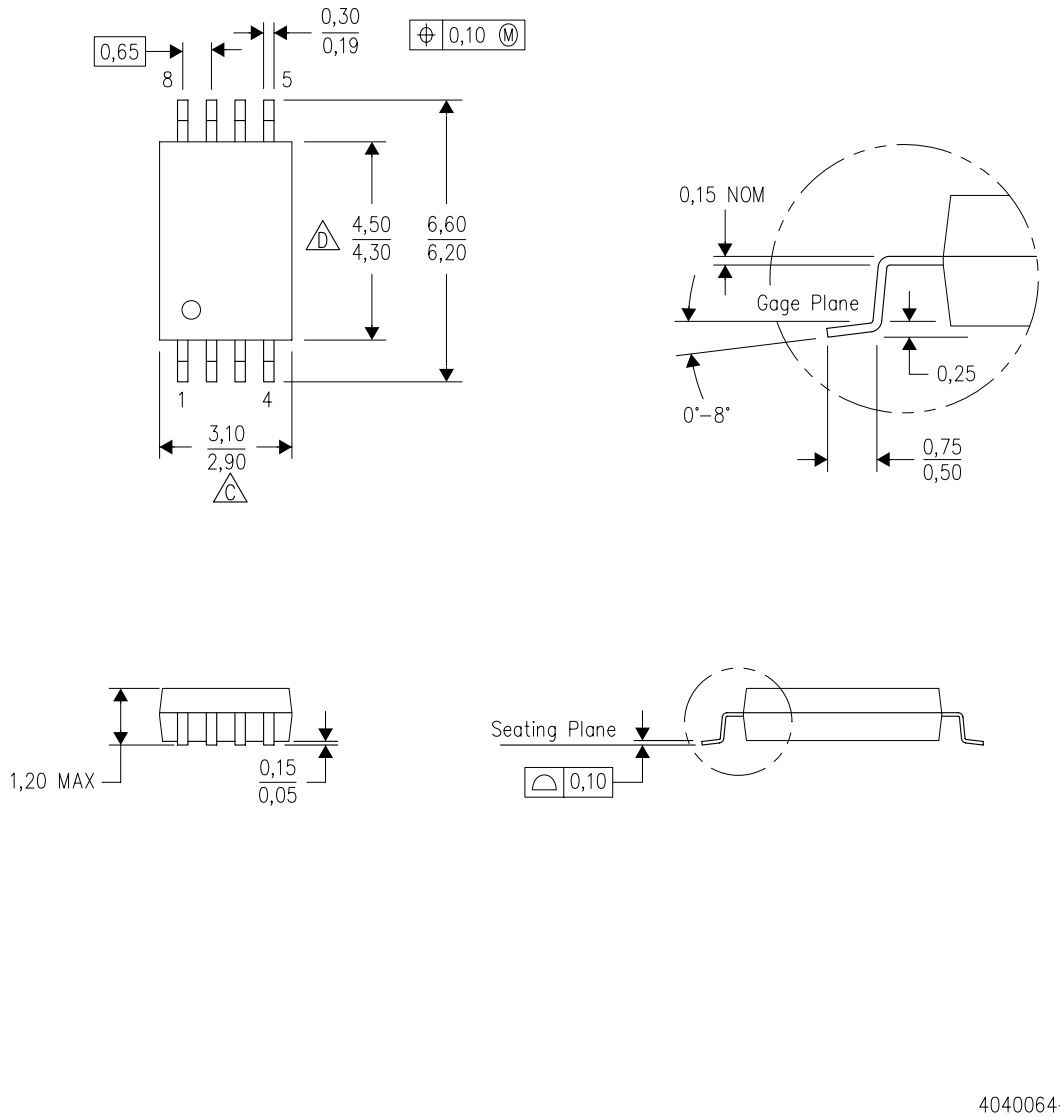
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R–PDSO–G8) PLASTIC SMALL OUTLINE



4040064–2/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

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